



四川索斯特电子有限公司
Sichuan Source-Set Electronics Co., Ltd
石英晶体规格书



规 格 书
SPECIFICATIONS

规格书编号/ID: _____

物料描述/

Product Description: SMD CRYSTAL SEAM 1.6*1.2

料号/

Part Number: SCOYR25X00000YLPM

制作人/

Approved by: 陈 丽

审核人/

Checked by: 陈晓群

日期/

Date: 2025/6/8

盖章/

Stamp: _____

客户签署/

Customer signature required

公司名称/

Company: _____

客户料号/

Customer Part Number: _____

承认人/

Approved by: _____

批准人/

Confirmed by: _____

日期/

Date: _____

盖章/

Stamp: _____

● ELECTRICAL PARAMETERS

地址/Addr: 四川省泸州市泸县工业园 B 区明星路 204 号(坤羽)五、六栋

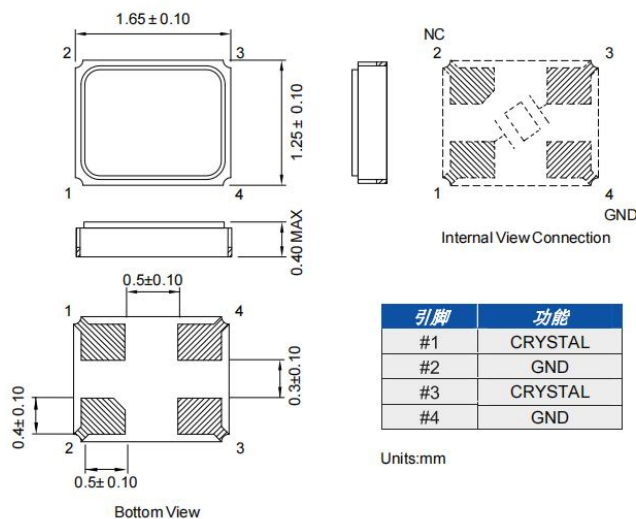
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谐振器产品技术指标	Min	Max	Units
1.Holder Type(型号规格)	SEAM 1.6*1.2		
2.Mode of Oscillation (振动模式)	Fundamental		
3.Frequency (标称频率)	25.000000		MHz
4.Load Capacitance (CL) (负载电容)	10		pF
5.Shunt Capacitance (Co) (静态电容)	0	2	pF
6.Equivalent Resistance (谐振电阻)		100	Ω
7.Frequency Tolerance at 25°C (调整频差)	-10	10	ppm
8.Stability over operation temperance (温度频差)	± 20		ppm
9.Insulation Resistance (at D.C. 100V) (绝缘电阻)	500		M Ω
10.Drive Level (激励功率)	100		uw
11.Operating Temperature Range (工作温度范围)	-40	85	°C
12.Storage Temperature Range (储存温度范围)	-40	125	°C
13.Aging (老化率)	± 3		ppm/year
14.Other(其他)	Moisture Sensitivity Level (零件湿敏等级) Level 1		

OUTLINE DIMENSIONS(UNIT:mm) 外形尺寸 (单位: mm)



● Marking (标记)

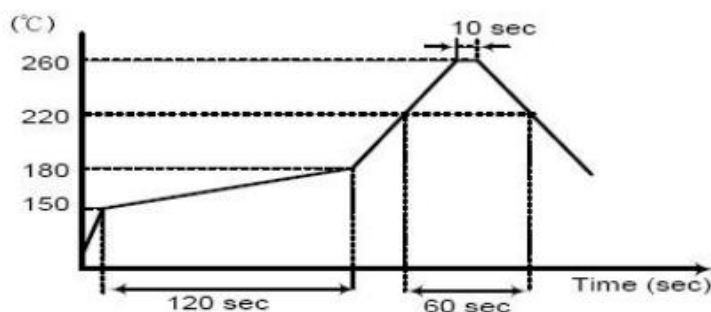
25.000
MHZ

● SUGGESTED REFLOW PROFILE (回流焊曲线图)

Total time: 200sec. Max. (总时间: 200秒 最大)

Solder melting point: 220℃ (熔点 220℃)

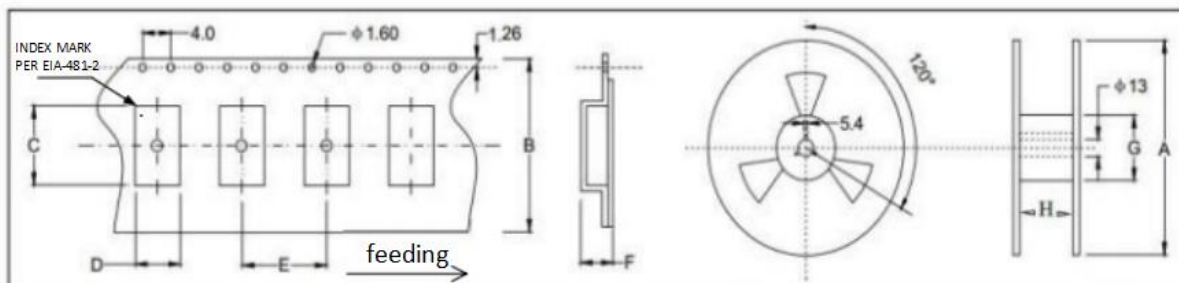
Profiles Feature (特性)		Pb-Free Assembly
Average Ramp-up Rate(Ts max to Tp)	平均升温速度	3℃/second Max
Preheat	预热	
■ Temperature Min (Ts min)	最低温度	125℃
■ Temperature Max (Ts max)	最高温度	200℃
■ Time (ts min to ts max)	从最低到最高时间	(60~180) seconds
Time maintained above	维持上述时间	
■ Temperature(T1)	温度	217℃
■ Time(tp)	时间	(60~150) seconds
Peak/Classification Temperature(Tp)	最高点温度	260℃
Time within 5℃ of actual Peak Temperature(tp)	高温维持时间	(20~40) seconds
Ramp-down rate	降温速度	6℃/second max
Time 25℃ to Peak Temperature	从25℃到最高温度的时间	8 minutes max
Suggest reflow times	建议 reflow次数	3 Times max



- PACKING (包装) 3Kpcs/REEL

编带尺寸图

Taping Dimensions



Size	A	B	C	D	E	F	G	H
SMD-1612	180±2.0	8.0±0.3	1.85±0.1	1.45±0.1	4.0±0.1	0.45±0.1	61.0±1.0	8.0±1.0
3000 pcs per reel								

● RELIABILITY SPECIFICATIONS (信赖度试验)			
No	Test Item (测试项目)	Test Conditions (测试条件)	Reference (参考)
1	High Temperature High Humidity Storage (高温、高湿、储存)	Temperature: 85°C±3°C 温度: 85°C±3°C Relative Humidity: 85%RH 相对湿度: 85%RH Time: 96 Hours 时间: 96小时	JIS C5023
2	High Temperature Storage (高温储存)	Temperature: 125°C±3°C 温度: 125°C±3°C Time: 96 Hours 时间: 96小时	MIL-STD-883E Method 1005.8
3	Low Temperature Storage (低温储存)	Temperature: -40°C±3°C 温度: -40°C±3°C Time: 96Hours 时间: 96小时	MIL-STD-883E Method 1013
4	Thermal Shock (温度冲击)	Temperature1: -55°C±5°C 温度1: -55°C±5°C Temperature2: 85°C±5°C 温度2: 85°C±5°C Temperature change between T1 and T2 5 min T1和T2温度在5分钟内改变 10cycles maintain T1 and T2 for 30 minutes each mone cycle 每次循环30分钟共10次	MIL-STD-202F Method 107 Condition
5	RESISTANCE TO SOLDER HEAT (耐焊接热)	Solder Temperature: 260°C±5°C 焊槽温度: 260°C±5°C Time: 10±1 Seconds 时间: 10±1秒	MIL-STD-202F Method 210E
6	Solderability(可焊性)	The solder pot temperature is 245±5°C, dwell time 5±0.5sec 245±5°C焊锡槽浸润5±0.5秒	J-STD-002B
7	Drop Test (落下试验)	3 Times Free Fall from 75cm height table to 3cm thickness hard wood board 从75cm高度3次跌落到3cm厚硬质木板上	JIS C6701
8	MECHANICAL SHOCK (机械冲击)	Half sine wave, 1000 G 半正弦波, 加速度1000G 3 Times for all 3 directions X、Y、Z 三个相互垂直方向各三次	MIL-STD-202F Method 213B
9	Vibration (机械振动)	Frequency Range: 10Hz~55Hz 频率范围: 10Hz~55Hz Amplitude: 0.75mm 振幅: 0.75mm 2 Hours in each direction, total 6 Hours X、Y、Z 三个相互垂直方向各振动2小时	MIL-STD-883E Method 2007.3
10	Leakage Test (气密性)	Take measurements with a helium Leakage detector 氦质检漏 Leakage Rate ≤ 1×10 ⁻³ Pa cm ³ /s 漏率 ≤ 1×10 ⁻³ Pa cm ³ /s	MIL-STD-883E